

FORTRON[®] 6850L6

Polyphenylene sulfide

Fortron 6850L6 offers the lowest warpage available. The easy flowing nature allows this product to be injection molded into thin walled applications. The excellent balance of mineral and glass fibers result in a superior heat resistance and dimensional stability. This grade is inherently flame-retardant along with high hardness and rigidity. Especially used for thin walled by unfavorable flow length-wall thickness ratio. This is the most isotropic grade available.

Product information

rioddol information			
Resin Identification	PPS-(GF+MD)5 0		ISO 1043
Part Marking Code	>PPS-(GF+MD)5	0<	ISO 11469
Rheological properties			
Moulding shrinkage range, parallel	0.3 - 0.6		ISO 294-4, 2577
Moulding shrinkage range, normal	0.4 - 0.6	%	ISO 294-4, 2577
Typical mechanical properties			
Tensile modulus	18500	MPa	ISO 527-1/-2
Tensile stress at break, 5mm/min	120	MPa	ISO 527-1/-2
Tensile strain at break, 5mm/min		%	ISO 527-1/-2
Flexural modulus	16800		ISO 178
Flexural strength		MPa	ISO 178
Compressive strength Charpy impact strength, 23°C		MPa kJ/m²	ISO 604 ISO 179/1eU
Charpy impact strength, -30°C		kJ/m ²	ISO 179/1eU
Charpy notched impact strength, 23°C		kJ/m ²	ISO 179/1eA
Charpy notched impact strength, -30°C		kJ/m ²	ISO 179/1eA
Izod notched impact strength, 23°C	4	kJ/m²	ISO 180/1A
Izod notched impact strength, -30 °C		kJ/m²	ISO 180/1A
Izod impact strength, 23°C		kJ/m²	ISO 180/1U
Izod impact strength, -30°C		kJ/m²	ISO 180/1U
Hardness, Rockwell, M-scale	96 0.33 ^[C]		ISO 2039-2
Poisson's ratio	0.33		
[C]: Calculated			
Thermal properties			
Melting temperature, 10°C/min	280		ISO 11357-1/-3
Glass transition temperature, 10°C/min		°C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	270		ISO 75-1/-2
Temperature of deflection under load, 8 MPa	215	°С Е-6/К	ISO 75-1/-2 ISO 11359-1/-2
Coefficient of linear thermal expansion (CLTE), parallel	15	E-0/K	150 11359-1/-2
Coefficient of linear thermal expansion (CLTE),	31	E-6/K	ISO 11359-1/-2
normal	•	_ 0/11	
Flammability			
Burning Behav. at 1.5mm nom. thickn.	V-0	class	IEC 60695-11-10
Thickness tested		mm	IEC 60695-11-10
Burning Behav. at thickness h		class	IEC 60695-11-10
Thickness tested	0.38	mm	IEC 60695-11-10

Printed: 2024-09-05



FORTRON[®] 6850L6

Polyphenylene sulfide

Electrical properties			
Dissipation factor, 1MHz	10	E-4	IEC 62631-2-1
Volume resistivity	>1E13	Ohm.m	IEC 62631-3-1
Surface resistivity	>1E15	Ohm	IEC 62631-3-2
Electric strength	25	kV/mm	IEC 60243-1
Comparative tracking index	225		IEC 60112
Arc Resistance	182	S	UL 746B
Physical/Other properties			
Water absorption, 2mm	0.02	%	Sim. to ISO 62
Water absorption, Immersion 24h	0.02	%	Sim. to ISO 62
Density	1800	kg/m³	ISO 1183
Injection			
Drying Recommended	yes		
Drying Temperature	130		
Drying Time, Dehumidified Dryer	2 - 4	h	
Processing Moisture Content	≤0.02	%	
Melt Temperature Optimum	330	°C	
Min. melt temperature	310	°C	
Max. melt temperature	340		
Screw tangential speed	0.2 - 0.3	m/s	
Mold Temperature Optimum	150	°C	
Min. mould temperature	140	-	
Max. mould temperature	160		
Hold pressure range	30 - 70		
Back pressure	3	MPa	

Characteristics

Additives

Release agent

Additional information

Processing Notes

Pre-Drying

FORTRON should in principle be predried. Because of the necessary low maximum residual moisture content the use of dry air dryers is recommended. The dew point should be =< - 30° C. The time between drying and processing should be as short as possible.

Storage

For subsequent storage the material should be stored dry in the dryer until processed (<= 60 h).

Printed: 2024-09-05



FORTRON[®] 6850L6

Polyphenylene sulfide

Printed: 2024-09-05

Revised: 2024-06-13 Source: Celanese Materials Database

NOTICE TO USERS: Values shown are based on testing of laboratory test specimens and represent data that fall within the standard range of properties for natural material. These values alone do not represent a sufficient basis for any part design and are not intended for use in establishing maximum, minimum, or ranges of values for specification purposes. Colourants or other additives may cause significant variations in data values. Properties of moulded parts can be influenced by a wide variety of factors including, but not limited to, material selection, additives, part design, processing conditions and environmental exposure. Other than those products expressly identified as medical grade (including by MT® product designation or otherwise), Celanese's products are not intended for use in medical or dental implants. Regardless of any such product designation, any determination of the suitability of a particular material and part design for any use contemplated by the users and the manner of such use is the sole responsibility of the users, who must assure themselves that the material as subsequently processed meets the needs of their particular product or use. To the best of our knowledge, the information contained in this publication is accurate; however, we do not assume any liability whatsoever for the accuracy and completeness of such information. The information contained in this publication as a promise or guarantee of specific properties of our products. It is the sole responsibility of the users to investigate whether any existing patents are infringed by the use of the materials mentioned in this publication. Moreover, there is a need to reduce human exposure to many materials to he lowest that they can meet all applicable safety and health standards. We strongly recommend that users seek and adhere to the manufacturer's current instructions for handling each material they use, and entrust the handling of such material to adequately trained personnel only. Please call the telephone numbers listed for

© 2024 Celanese or its affiliates. All rights reserved. Celanese®, registered C-ball design and all other trademarks identified herein with ®, TM, SM, unless otherwise noted, are trademarks of Celanese or its affiliates. Fortron is a registered trademark of Fortron Industries LLC. KEPITAL is a registered trademark of Korea Engineering Plastics Company, Ltd.

Page: 3 of 3